

Abstract

Method for producing semiconductor wafers by means of a wire saw

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Method for producing semiconductor wafers from a workpiece by processing the workpiece by means of a wire saw, comprising feeding the workpiece through an arrangement of wires which are tensioned between wire guide rollers and move in a running direction;

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producing kerfs when the wires engage into the workpiece; determining a placement error of the kerfs; and inducing a compensating movement of the workpiece as a function of the determined placement error along a longitudinal axis of the workpiece during the feeding of the workpiece through the arrangement of wires.

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Drawing for the abstract: Fig.2